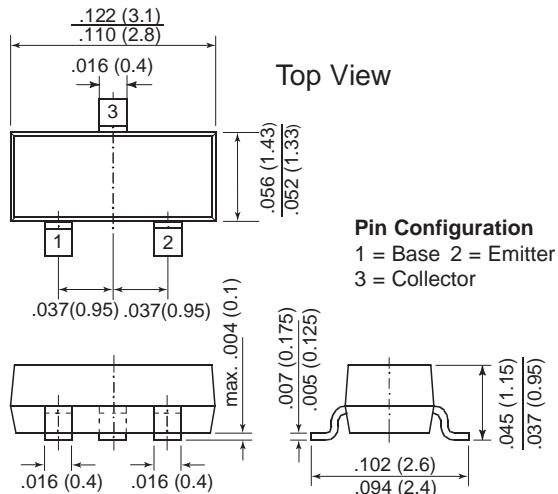
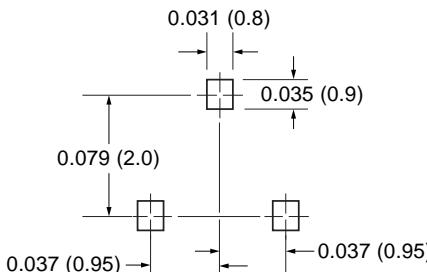



TO-236AB (SOT-23)

Mounting Pad Layout

Mechanical Data
Case: SOT-23 Plastic Package

Weight: approx. 0.008 grams

Marking BC807-16 = 5A BC808-16 = 5E
Codes: -25 = 5B -25 = 5F
 -40 = 5C -40 = 5G

Packaging Codes/Options:

 E8/10K per 13" reel (8mm tape), 30K/box
 E9/3K per 7" reel (8mm tape), 30K/box

Features

- PNP Silicon Epitaxial Planar Transistors for switching, AF driver and amplifier applications.
- Especially suited for automatic insertion in thick and thin-film circuits.
- These transistors are subdivided into three groups (-16, -25, and -40) according to their current gain.
- As complementary types, the NPN transistors BC817 and BC818 are recommended.

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage (Base shorted) BC807 BC808	-V _{CES}	50 30	V
Collector-Emitter Voltage (Base open) BC807 BC808	-V _{CEO}	45 25	V
Emitter-Base Voltage	-V _{EBO}	5	V
Collector Current	-I _C	800	mA
Peak Collector Current	-I _{CM}	1000	mA
Peak Base Current	-I _{BM}	200	mA
Peak Emitter Current	I _{EM}	1000	mA
Power Dissipation at T _{SB} = 50 °C	P _{tot}	310 ⁽¹⁾	mW
Thermal Resistance Junction to Ambient Air	R _{θJA}	450 ⁽¹⁾	°C/W
Thermal Resistance Junction to Substrate Backside	R _{θSB}	320 ⁽¹⁾	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _s	-65 to +150	°C

Note: (1) Device on fiberglass substrate, see layout on next page.

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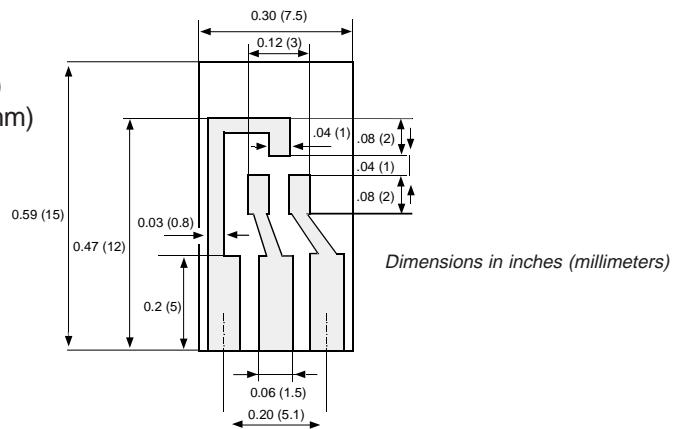
Small Signal Transistors (PNP)
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DC Current Gain	h_{FE}	$-V_{CE} = 1\text{V}, -I_C = 100\text{mA}$	100	—	250	—
		$-V_{CE} = 1\text{V}, -I_C = 500\text{mA}$	160	—	400	—
		$-V_{CE} = 1\text{V}, -I_C = 500\text{mA}$	250	—	600	—
		$-V_{CE} = 1\text{V}, -I_C = 500\text{mA}$	40	—	—	—
Collector Saturation Voltage	$-V_{CESat}$	$-I_C = 500\text{mA}, -I_B = 50\text{mA}$	—	—	0.7	V
Base Saturation Voltage	V_{BESat}	$-I_C = 500\text{mA}, -I_B = 50\text{mA}$	—	—	1.3	V
Base-Emitter Voltage	$-V_{BEon}$	$-V_{CE} = 1\text{V}, -I_C = 500\text{mA}$	—	—	1.2	V
Collector-Base Cutoff Current	$-I_{CBO}$	$-V_{CB} = 20\text{V}$ $-V_{CB} = 20\text{V}, T_J = 150^\circ\text{C}$	—	—	100	nA
Emitter-Base Cutoff Current	$-I_{EBO}$	$-V_{EB} = 4\text{ V}$	—	—	100	nA
Gain-Bandwidth Product	f_T	$-V_{CE} = 5\text{V}, -I_C = 10\text{mA}$ $f = 50\text{ MHz}$	—	100	—	MHz
Collector-Base Capacitance	C_{CBO}	$-V_{CB} = 10\text{V}, f = 1\text{ MHz}$	—	12	—	pF

Note: (1)Device on fiberglass substrate, see layout.

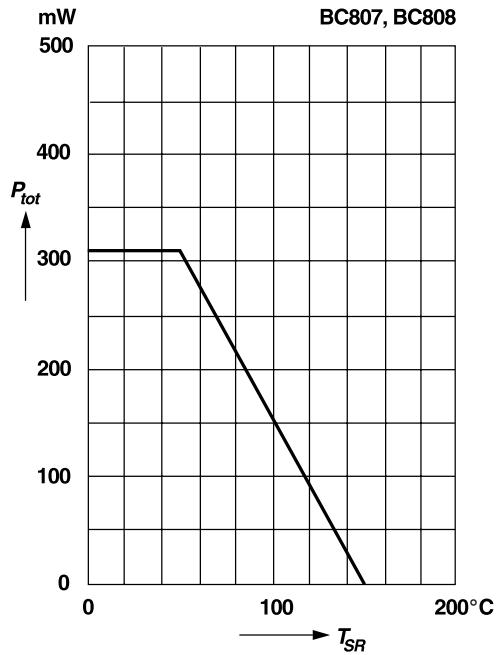
Layout for $R_{\theta JA}$ test

Thickness: Fiberglass 0.059 in. (1.5 mm)
Copper leads 0.012 in. (0.3 mm)

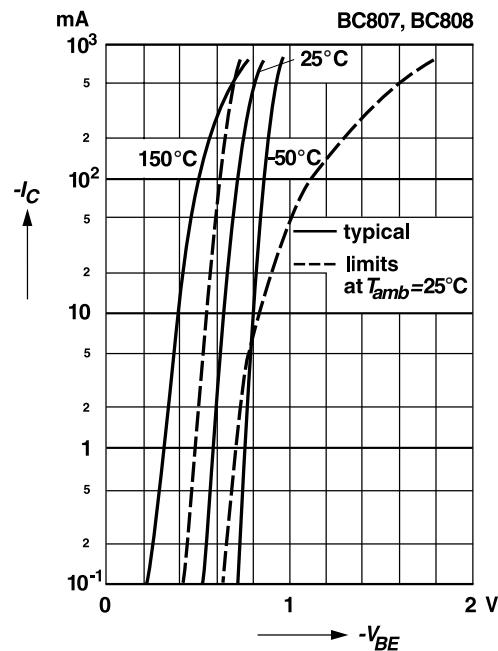


Small Signal Transistors (PNP)

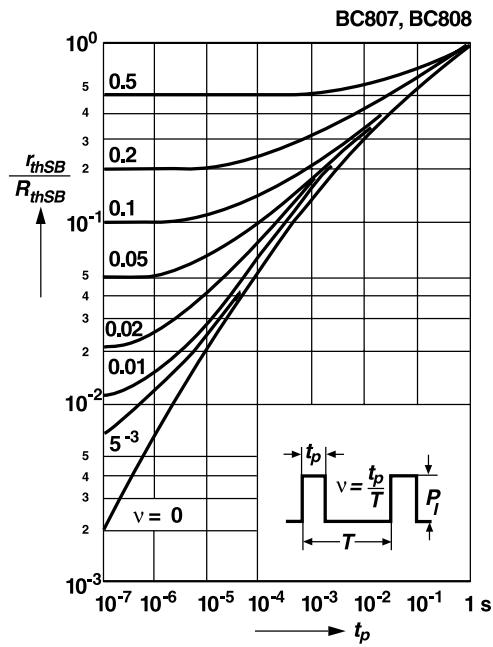
**Admissible power dissipation
versus temperature of substrate backside**
Device on fiberglass substrate, see layout



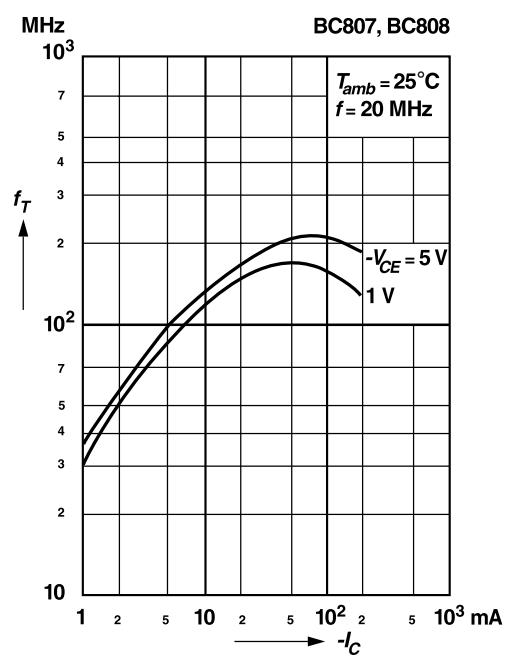
**Collector current
versus base-emitter voltage**



**Pulse thermal resistance
versus pulse duration (normalized)**
Device on fiberglass substrate, see layout

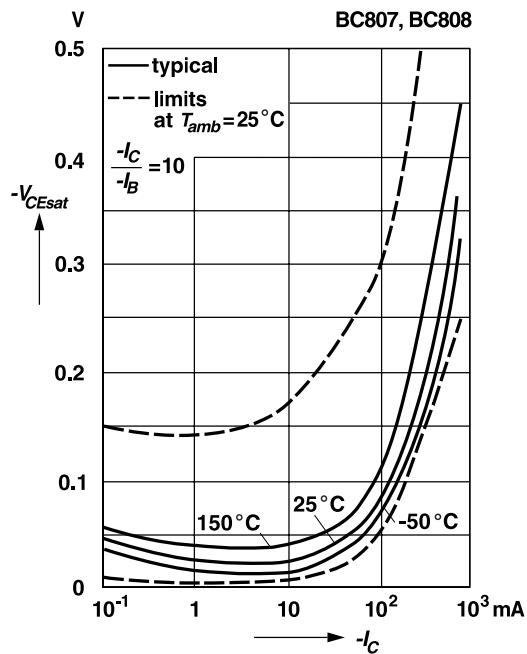


**Gain-bandwidth product
versus collector current**

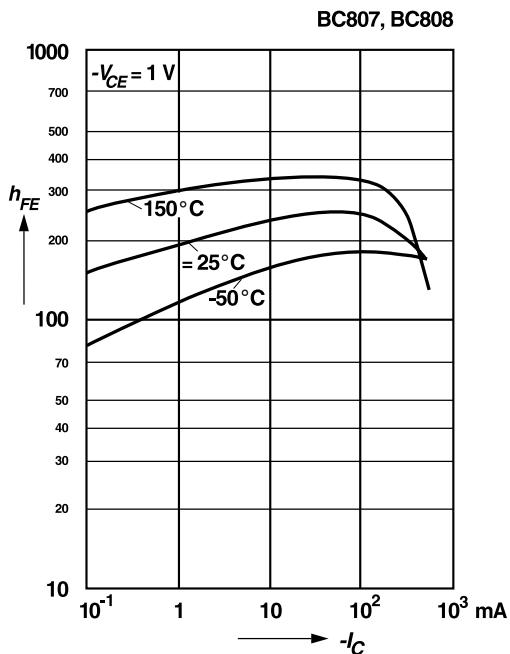


Small Signal Transistors (PNP)

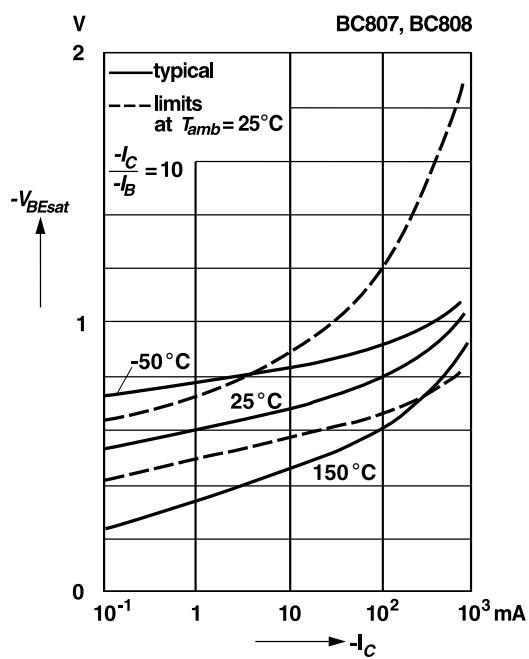
Collector saturation voltage
versus collector current



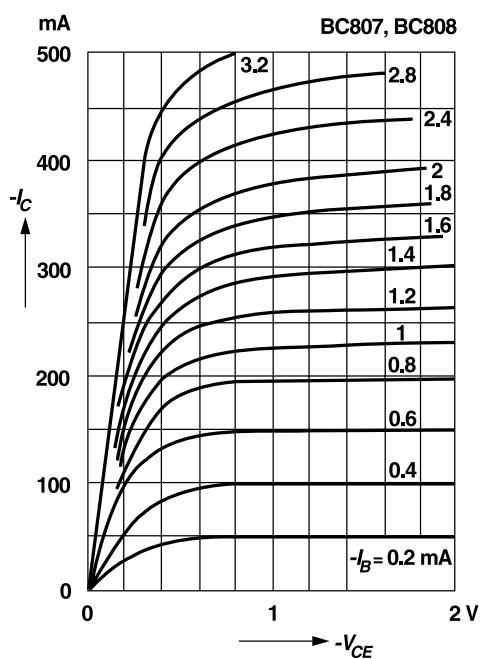
DC current gain
versus collector current



Base saturation voltage
versus collector current

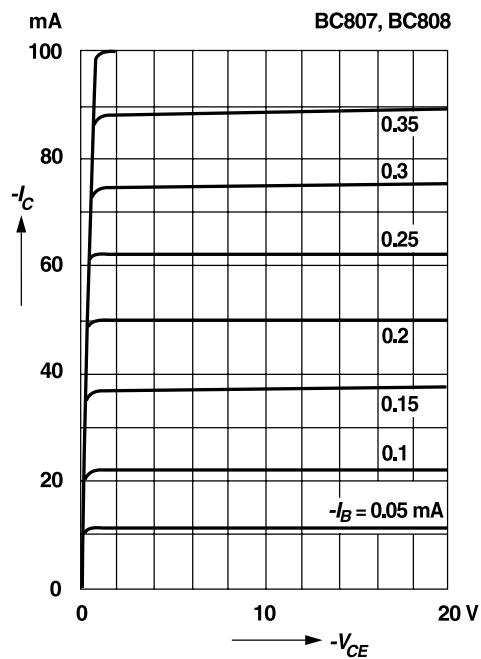


Common emitter
collector characteristics



Small Signal Transistors (PNP)

Common emitter
collector characteristics



Common emitter
collector characteristics

